

ductruong

\* \* \* \* \* STN Columbus \* \* \* \* \*

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COST IN U.S. DOLLARS	SINCE FILE ENTRY	TOTAL SESSION
FULL ESTIMATED COST	0.21	0.21

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FILE 'USPATFULL' ENTERED AT 11:19:49 ON 15 DEC 2008

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FILE 'USPATOLD' ENTERED AT 11:19:49 ON 15 DEC 2008

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FILE 'USPAT2' ENTERED AT 11:19:49 ON 15 DEC 2008

CA INDEXING COPYRIGHT (C) 2008 AMERICAN CHEMICAL SOCIETY (ACS)

=> s thermoplastic polyimide# and imide oligomer#

L1 32 THERMOPLASTIC POLYIMIDE# AND IMIDE OLIGOMER#

=> s l1 and aromatic tetracarboxylic acid dianhydride#

L2 3 L1 AND AROMATIC TETRACARBOXYLIC ACID DIANHYDRIDE#

=> s l2 and diamine#

L3 1 L2 AND DIAMINE#

=> d

L3 ANSWER 1 OF 1 USPATFULL on STN

AN 2006:289415 USPATFULL

TI Novel thermoplastic polyimide and inide oligomer

IN Inoue, Shinsuke, Hiroshima, JAPAN

Nanba, Satoru, Hiroshima, JAPAN

Inagaki, Hiroyasu, Tokyo, JAPAN

PI US 20060247411 A1 20061102

AI US 2003-528530 A1 20030918 (10)

WO 2003-JP11873 20030918

20050318 PCT 371 date

DT Utility

FS APPLICATION

ductruong

LN.CNT 672  
INCL INCLM: 528/170.000  
NCL NCLM: 528/170.000  
IC IPCI G01N0033-00 [I,A]  
IPCR G01N0033-00 [I,C]; G01N0033-00 [I,A]  
CAS INDEXING IS AVAILABLE FOR THIS PATENT.

=> s l2 and triple bond#  
L4 1 L2 AND TRIPLE BOND#

=> d

L4 ANSWER 1 OF 1 USPATFULL on STN  
AN 2006:289415 USPATFULL  
TI Novel thermoplastic polyimide and inide oligomer  
IN Inoue, Shinsuke, Hiroshima, JAPAN  
Nanba, Satoru, Hiroshima, JAPAN  
Inagaki, Hiroyasu, Tokyo, JAPAN  
PI US 20060247411 A1 20061102  
AI US 2003-528530 A1 20030918 (10)  
WO 2003-JP11873 20030918  
20050318 PCT 371 date

DT Utility  
FS APPLICATION

LN.CNT 672  
INCL INCLM: 528/170.000  
NCL NCLM: 528/170.000  
IC IPCI G01N0033-00 [I,A]  
IPCR G01N0033-00 [I,C]; G01N0033-00 [I,A]  
CAS INDEXING IS AVAILABLE FOR THIS PATENT.

=> s l3 and (PEPA or phenylethynyl phthalic acid anhydride# or  
phenylethynylphthalic acid anhydride#)  
L5 1 L3 AND (PEPA OR PHENYLETHYNYL PHTHALIC ACID ANHYDRIDE# OR PHENY  
LETHYNLPHTHALIC ACID ANHYDRIDE#)

=> d l2 1-3

L2 ANSWER 1 OF 3 USPATFULL on STN  
AN 2006:289415 USPATFULL  
TI Novel thermoplastic polyimide and inide oligomer  
IN Inoue, Shinsuke, Hiroshima, JAPAN  
Nanba, Satoru, Hiroshima, JAPAN  
Inagaki, Hiroyasu, Tokyo, JAPAN  
PI US 20060247411 A1 20061102  
AI US 2003-528530 A1 20030918 (10)  
WO 2003-JP11873 20030918  
20050318 PCT 371 date

DT Utility  
FS APPLICATION

LN.CNT 672  
INCL INCLM: 528/170.000  
NCL NCLM: 528/170.000  
IC IPCI G01N0033-00 [I,A]  
IPCR G01N0033-00 [I,C]; G01N0033-00 [I,A]  
CAS INDEXING IS AVAILABLE FOR THIS PATENT.

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L2 ANSWER 2 OF 3 USPATFULL on STN  
AN 2002:258598 USPATFULL  
TI Underfill material for COF mounting and electronic components  
IN Yamaguchi, Hiroaki, Tokyo, JAPAN  
Kohda, Masafumi, Ichihara City, JAPAN  
PA UBE INDUSTRIES, LTD., UBE CITY, JAPAN (non-U.S. corporation)  
PI US 20020142167 A1 20021003  
US 6613449 B2 20030902  
AI US 2002-58112 A1 20020129 (10)  
PRAI JP 2001-20399 20010129  
DT Utility  
FS APPLICATION  
LN.CNT 507  
INCL INCLM: 428/413.000  
INCLS: 528/403.000  
NCL NCLM: 428/620.000; 428/413.000  
NCLS: 257/791.000; 257/792.000; 257/793.000; 257/E21.503; 257/E23.119;  
528/027.000; 528/117.000; 528/405.000; 528/418.000; 528/403.000  
IC [7]  
ICM B32B027-38  
ICS C08G059-00  
IPCI B32B0027-38 [ICM,7]; C08G0059-00 [ICS,7]  
IPCI-2 H01L0029-12 [ICM,7]; H01L0029-02 [ICM,7,C\*]  
IPCR H01L0023-16 [I,C\*]; H01L0023-18 [I,A]; C08G0059-00 [I,C\*];  
C08G0059-40 [I,A]; H01L0021-02 [I,C\*]; H01L0021-56 [I,A];  
H01L0023-28 [I,C\*]; H01L0023-29 [I,A]  
CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L2 ANSWER 3 OF 3 USPAT2 on STN  
AN 2002:258598 USPAT2  
TI Underfill material for COF mounting and electronic components  
IN Yamaguchi, Hiroaki, Tokyo, JAPAN  
Kohda, Masafumi, Ichihara, JAPAN  
PA UBE Industries, Ltd., Yamaguchi, JAPAN (non-U.S. corporation)  
PI US 6613449 B2 20030902  
AI US 2002-58112 20020129 (10)  
PRAI JP 2001-20399 20010129  
DT Utility  
FS GRANTED  
LN.CNT 492  
INCL INCLM: 428/620.000  
INCLS: 257/791.000; 257/792.000; 257/793.000; 528/027.000; 528/117.000;  
528/405.000; 528/418.000  
NCL NCLM: 428/620.000; 428/413.000  
NCLS: 257/791.000; 257/792.000; 257/793.000; 257/E21.503; 257/E23.119;  
528/027.000; 528/117.000; 528/405.000; 528/418.000; 528/403.000  
IC [7]  
ICM H01L029-12  
IPCI B32B0027-38 [ICM,7]; C08G0059-00 [ICS,7]  
IPCI-2 H01L0029-12 [ICM,7]; H01L0029-02 [ICM,7,C\*]  
IPCR H01L0023-16 [I,C\*]; H01L0023-18 [I,A]; C08G0059-00 [I,C\*];  
C08G0059-40 [I,A]; H01L0021-02 [I,C\*]; H01L0021-56 [I,A];  
H01L0023-28 [I,C\*]; H01L0023-29 [I,A]  
EXF 257/791; 257/792; 257/793; 428/620; 528/27; 528/117; 528/405; 528/418  
CAS INDEXING IS AVAILABLE FOR THIS PATENT.

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